



HCD High Density 288MB SO-RIMM First to Market with Rambus Validation

SUNNYVALE, May 30, 2001 – In the race towards availability of high density SO-RIMM memory modules, HCD succeeds in being first to market 288MB SO-RIMMs in Q2 of 2001. HCD's 288MB ECC configuration is the first high density SO-RIMM to receive Rambus™ validation and listing on the Rambus Developers site.

Development for the high density module was prompted by key telecom OEMs seeking the high bandwidth, low pin-count of Rambus technology products within a condensed, standardized form factor. Previously available SO-RIMMs were limited to a density range of 32MB to 144MB. Demand for higher density components offering the high performance of full size RIMMs while conforming to the space constrained requirements of many networking applications was a challenge being addressed by several leading modular subsystem manufacturers. HCD was able to exceed these requirements by designing a high density SO-RIMM that dimensionally conforms to the current SO-RIMM form factor.

"HCD's high density SO-RIMM integrates into the same dimensional form factor as the current SO-RIMM, highlighting our design expertise and ability to meet strict customer needs," said Ann Ciurczak, Product Manager for Standard Products at HCD. "Not only did we meet all customer requirements, HCD's quick-turn design and manufacturing capabilities put us ahead of other leading module manufacturers for the 288MB SO-RIMM."

"HCD's continued support of Rambus products along with their high frequency design expertise for products like the high density SO-RIMM will help to ensure the implementation and adoption of this advanced technology for networking and communications applications," stated Wade Appelman, Vice President of Marketing Advanced Networking Products at Vitesse Semiconductor Corporation. "Our IQ2000™ family of network processors is specifically designed to support Rambus technology in high performance networking and communications equipment which in turn drives the need for high density SO-RIMMs."

Scheduled for volume availability in June 2001, the 288MB module is one offering from the HCD SO-RIMM product family, which ranges in frequency from 600MHz to 800MHz and in densities up to 288MB in both ECC and non-ECC configurations. The addition of the high density SO-RIMM to HCD's Module Product Line completes the industry's most robust selection of RIMM offerings.

About High Connection Density Inc.:

High Connection Density Inc. (HCD) is a premier supplier of advanced memory modules and high performance modular subsystems. Focusing on modular solutions enabling the transition to next generation systems, HCD's expertise in packaging, thermal and mechanical design, and manufacturing position HCD to be a premier source of modular subsystems and solutions for high performance electronic applications. To learn more about HCD products and services, visit the website at www.hcdcorp.com.



HIGH CONNECTION DENSITY, INC.
www.hcdcorp.com

About Vitesse Semiconductor Corporation

Vitesse Semiconductor Corporation is a leading designer and supplier of innovative, high-performance integrated circuits (ICs) used in next generation networking and optical communications equipment. The company's products address the needs of Enterprise, Access, Metro, Core, and Optical Transport network equipment manufacturers who demand a robust combination of high speed, high service delivery and low power dissipation in their components. Vitesse is headquartered in Camarillo, Calif., and operates two fabrication facilities; one in Camarillo and one in Colorado Springs, Colo. Company and product information can be found on the web at www.vitesse.com or is available by calling 1-800-VITESSE.